

Technical Data

Schroff PXI - Backplanes

part# 23006 – 57n & 58n

Mechanical and Climatic Parameters	Standard	on request
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Operating Temperature	0°C - +70°C	
Storage Temperature	-55°C - +105°C	
Humidity conformal coating	max 95%, not condensing	on request
Flammability: <ul style="list-style-type: none"> • PCB, Connectors • Ceramic caps 	UL 94 V-0 fire-proof	
Connectors <ul style="list-style-type: none"> • Performance level per IEC 61076-4-101 • Mechanical Durability (Mating Cycles) • Total Insertion and Extraction Force (mating) 	IEC 61076-4-101 (HardMetric 2mm Grid) level 2 > 250 cycles < 0,7 N / Pin	level 1 > 500 cycles
Vibration acc. DIN 41640 Part 15	10Hz – 500Hz 5g rms	5Hz – 2000Hz 20g rms
Shock (10 pulses each direction x,y,z)	10g, 6ms	
Low Pressure / Altitude (if max Board voltage per single isolation gap doesn't exceed 12V)	no restrictions	
Construction:	12 - Layer Stripline	
Dimensions (mm) <ul style="list-style-type: none"> • Width (pl. see Dwg.) • Height 3U / 6U • Thickness 	20,32mm x # Slots-1mm 128,7mm / 262,05 mm 3,9 mm +/- 0,2 mm	

Electrical Parameters:

Specifications	PICMG 2.0 R3.0 CPCI Core Specification PICMG 2.1 CPCI Hot Swap Specification PICMG 2.6 Bridging Specification PICMG 2.8 Pin Registration for PXI PICMG 2.9 System Management Bus Spec. PICMG 2.10 Keying Specification PXI Spec PXI Specification Rev. 2.0	
Service Life: MTBF, acc. to MIL HDBK 217F, cond.: 25°C, ground, benign 3U 8-Slot	more than 600.000h	
Characteristic Impedance PCI Bus PXI Local Bus	65 Ω ± 10 % 75 Ω ± 10 %	
Ohmic Resistance of Signal Tracks PCI Bus PXI Local Bus	< 80mΩ/Slot < 90mΩ/Slot	
Hot Swap	supported	

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Electrical Parameters (II):

Termination (only 8 Slot Backplanes)	Schottky diodes (on request), pluggable termination board
Power input	<ul style="list-style-type: none"> • Power bugs for wiring or • special Adapter Board to use an ATX cable; this board can act as a power distribution star point within the Systems
max. Current Carrying Capacity	10 A per Slot
<ul style="list-style-type: none"> • 5V/GND • 3,3V/GND 	10 A per Slot
max. Voltage Drop on +5V or +3,3V	< 40mV
VI/O	+5V (default), blue key; 3,3V optional (yellow key)
<ul style="list-style-type: none"> • bridging (default) • on request 	<ul style="list-style-type: none"> • field changeable, using M4 screws and a bus bar • fixed during bp assy by using a Power Bug cable loop using Faston crimp contacts
PCI Clock frequency	33 MHz (66MHz up to 5 Slots)
PCI Bus Width	64bit
Data Transfer Rate (peak)	132 Mbyte/s (32 bit) / 264 Mbyte/s (64 bit)
<ul style="list-style-type: none"> • 33 MHz • 66 MHz 	264 Mbyte/s (32 bit) / 528 Mbyte/s (64 bit)
Bridging of Backplanes clock frequency:	Backplanes of slot numbers equal or higher than 4 up to 7 Slots can be bridged
<ul style="list-style-type: none"> primary / secondary • 33 MHz / 33MHz • 66 MHz / 33MHz • 66 MHz / 66MHz 	<ul style="list-style-type: none"> primary / secondary • any slot number as primary and secondary b/p • 4 Slots / any Slot number • 4 Slot / 4 Slot
PXI Clock	10 MHz
<ul style="list-style-type: none"> • accuracy 	skew: < 0,5ns; <1,0ns for segmented Backplanes Jitter: < 0,2ns
<ul style="list-style-type: none"> • switching between external and internal sources, ♦ min Pulse width: ♦ min time between successive edges of the same polarity: 	> 30ns > 80ns